Fast, High-Voltage Drive, 6-Channel Output DecDriver™ Decimating LCD Panel Driver

AD8380

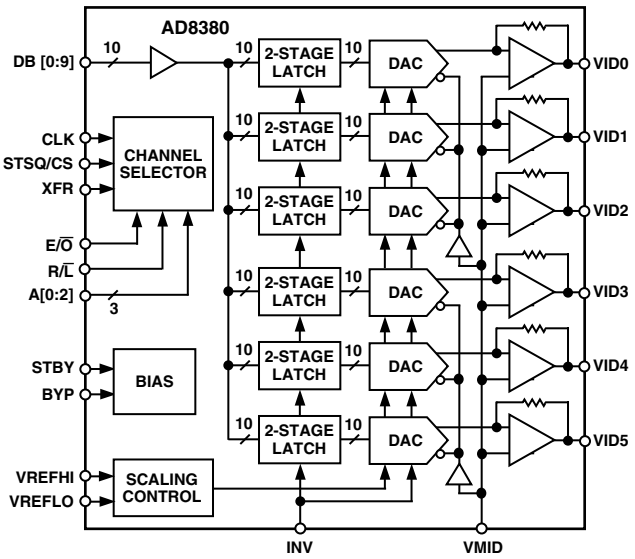
FEATURES

High-Voltage Drive to Within 1.3 V of Supply Rails
24 V Supply for Fast Output Voltage Drivers
High Update Rates: Fast 75 Ms/s 10-Bit Input Word Rate
Low Power Dissipation, 550 mW with Power-Down
Voltage Controlled Video Reference and Full-Scale (Contrast) Output Levels
INV Bit Reverses Polarity of Video Signal
Nominal 3.3 V Logic and 15 V Analog Supplies
Flexible Logic
Addressable or Sequential Channel Loading
STSQ/CS Allow Parallel AD8380 Operation for XGA and Greater Resolution
Drives Capacitive Loads
26 ns Settling Time to 1% Up to 150 pF Load
Slew Rate 270 V/μs
Available in 44-Lead MQFP

APPLICATIONS

Poly Si LCD Panel Analog Column Driver

FUNCTIONAL BLOCK DIAGRAM



PRODUCT DESCRIPTION

The AD8380 provides a fast, 10-bit latched decimating digital input that drives 6-channel high voltage drive outputs. The 10-bit input word is sequentially muxed into six separate high speed, bipolar DACs. Flexible digital input formats allow several AD8380s to be used in parallel for higher resolution displays. STSQ/CS, in conjunction with 3-bit addressable channel-loading pins, allows loading of the digital words either sequentially or randomly, and R/$\overline{L}$ control sets loading as either left to right, or vice versa. 6-channel high voltage output drivers drive to within 1.3 V of the rails to rated settling time. The output signal can be adjusted for dc signal reference, signal inversion or contrast for maximum flexibility.

The AD8380 is fabricated on ADI's XFCB26 fast bipolar 26 V process, providing fast input logic, trimmed accuracy bipolar DACs and fast settling, high voltage precision drive amplifiers on the same chip.

The AD8380 dissipates nominally 0.55 W of static power. STBY pin reduces power to a minimum, with fast recovery.

The AD8380 is offered in a 44-lead 10 × 10 × 2.0 mm MQFP package and operates over the commercial temperature range of 0°C to 85°C.

DecDriver is a trademark of Analog Devices, Inc.

REV. B

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AD8380–SPECIFICATIONS (@ 25°C, AVCC = 15 V, DVCC = 3.3 V, T_{MIN} = 0°C, T_{MAX} = 85°C, unless otherwise noted)

Model	Conditions	Min	Typ	Max	Unit
VIDEO DC PERFORMANCE[1]	T_{MIN} to T_{MAX}				
VDE	DAC Code = 450 to 800	–7.5	+1	+7.5	mV
VCME	DAC Code = 450 to 800	–3.5	+0.5	+3.5	mV
Scale Factor Error	DAC Code = 0 to 1023	–0.25		+0.25	%
Offset Error	DAC Code = 0 to 1023	–7	+1	+7	mV
REFERENCE INPUTS					
VMID Range[2]		6	7	7.5	V
VMID Bias Current			3		µA
VFS Range	VFS = 2 × (VREFHI–VREFLO)	1	5	6	V
VREFHI		VREFLO +0.5	AVCC – 2.5	AVCC	V
VREFLO		VMID – 0.5	VREFHI – 2.5	VREFHI – 0.5	V
VREFHI Input Resistance	to VREFLO		3.3		kΩ
VREFLO Bias Current			0.2		µA
VREFHI Input Current[3]	VFS = 5 V		750		µA
RESOLUTION					
Coding	Binary	10			Bits
DIGITAL INPUT CHARACTERISTICS					
Input Data Update Rate			75		Ms/s
Clock to Data Setup Times: t_1		1			ns
Clock to STSQ Setup Times: t_3		1			ns
Clock to XFR Setup Times: t_5		1			ns
Maximum CLK Rise and Fall Time, t_7		4			ns
Clock to A[0:2] Hold Times: t_9		4			ns
Clock to Data Hold Times: t_2		4			ns
Clock to STSQ Hold Times: t_4		4			ns
Clock to XFR Hold Times: t_6		4			ns
Clock to A[0:2] Setup Times: t_8		1			ns
C_{IN}				3	pF
I_{IN}			0.6		µA
V_{IH}		2.0			V
V_{IL}				0.8	V
V_{TH}	Threshold Voltage		1.4		V
VIDEO OUTPUT CHARACTERISTICS					
Output Voltage Swing	AVCC – V_{OH}, V_{OL} – AVEE		1.1	1.3	V
CLK to VID Delay[4]	50% of VIDx	13.5	15.5	17.5	ns
Output Current		30			mA
VIDEO OUTPUT DYNAMIC PERFORMANCE	T_{MIN} to T_{MAX}, V_O = 5 V Step, C_L = 150 pF, R_S = 25 Ω				
Data Switching Slew Rate			270		V/µs
Invert Switching Slew Rate			625		V/µs
Data Switching Settling Time to 1%[5]			26	32	ns
Data Switching Settling Time to 0.25%			35	65	ns
Invert Switching Settling Time to 1%[5]			30	40	ns
Invert Switching Settling Time to 0.25%			85	100	ns
CLK Feedthrough[6]			2	5	mV p-p
All-Hostile Crosstalk[7]					
Amplitude			95		mV p-p
Glitch Duration			40		ns
POWER SUPPLY					
Supply Rejection (VDE)	$+V_S$ = 15 V ± 1 V		1		mV/V
DVCC, Operating Range		3		5.5	V
DVCC, Quiescent Current			22	35	mA
AVCC, Operating Range		9		24	V
Total AVCC Quiescent Current			33	44	mA
STBY AVCC Current	STBY = H		0.5	5	mA
STBY DVCC Current	STBY = H		0.1	5	mA
OPERATING TEMPERATURE RANGE		0		85	°C

NOTES

[1]For definitions of VDE and VCME, see the Transfer Function section. Scale factor error is expressed as percentage of VFS.

[2]See Figure 1 for valid ranges of VMID.

[3]VREFHI Input Current = (VREFHI – VREFLO)/(VREFHI Input Resistance) = 2.5 V/3.3 kΩ.

[4]Delay time from 50% of falling CLK edge to 50% of output change. Measurement is made for both states of INV.

[5]For best settling time results, use minimum series output resistance, R_S of 25 Ω.

[6]An output channel is selected, and glitch is monitored as CLK is driven. STSQ and XFR are set to logic low.

[7]Input data is loaded such that any five output channels change by VFS (i.e., 5 V), and the sixth unselected channel is monitored. Measurement is made for both states of INV.

Specifications subject to change without notice.

PIN FUNCTION DESCRIPTIONS

Pin No.	Mnemonic	Description
1	NC	No Connect.
2–11	DB[0:9]	Video Data Inputs. DB9 is the MSB.
12	E/$\overline{O}$	Even/Odd data select, input latches are loaded at the falling edge of CLK if E/$\overline{O}$ is low or rising edge if E/$\overline{O}$ is high.
13	R/$\overline{L}$	Determines starting point of internally generated channel-loading sequence. R/$\overline{L}$ Low (when address = 111) loads from Channel 0 up to Channel 5.
14	INV	When high, analog video outputs are above the VMID setpoint. See Figure 3.
15, 16	DVEE, DVCC	Digital Supplies. Nominally 3.3 V and 0 V, respectively.
17, 20, 22, 24, 26, 28, 30, 32, 34, 37, 38	AVCCxxx, AVEExxx	Analog Supplies. Nominally 15 V and 0 V, respectively.
18	STBY	Stand By. When high, all digital and analog circuits are "debiased" and the power dissipation drops to a minimum.
19	BYP	An external capacitor connected from here to V_{EE} will help to ensure rapid DAC settling time.
21	VMID	Externally supplied voltage applied here sets the midpoint reference for the video output.
23, 25, 27, 29, 31, 33	VID5–VID0	Analog Video Outputs.
36, 35	VREFHI, VREFLO	Voltage between these pins sets DAC full-scale range. An external reference must be applied and should be common to all devices to ensure best tracking.
39–41	A[0:2]	3-bit channel address for addressable loading of the digital input latches.
42	STSQ/CS	STSQ to start internal sequencing or Chip Select to enable addressable channel addressing. See functional description. Used in conjunction with A[0:2].
43	XFR	If XFR = HIGH at the rising edge of CLK, data is transferred to the DACs on the next falling edge of CLK. See Figures 4, 6, 7, and 8.
44	CLK	Master Clock Input.

CHANNEL SELECTION FUNCTIONALITY

There are two channel selection modes, addressed channel loading, (in which the user directly controls which DAC is loaded), and internally sequenced loading (in which the user controls the direction and clock phase in which the loading proceeds).

ADDRESSED CHANNEL LOADING:

When channel address (A0, A1, A2) = 000 through 101, the video data is loaded into Channels 0 through 5. (STSQ/CS functions as "Chip Selection" this case.)

INTERNALLY SEQUENCED LOADING:

When channel address = 111 the video data is loaded in a sequence determined internally. The sequencing is initiated by a pulse applied to STSQ/CS input. The count proceeds from 0 to 5 if R/$\overline{L}$ is LOW or from 5 to 0 if R/$\overline{L}$ is HIGH.

DAC TRANSFER FUNCTION

$$V_{OUT} = VMID + VFS \times (1 - N/1023); \text{ if INV is HIGH,}$$

$$V_{OUT} = VMID - VFS \times (1 - N/1023); \text{ if INV is LOW}$$

where $VFS = 2 \times (\text{VREFHI} - \text{VREFLO})$

MAXIMUM OUTPUT VOLTAGE

The maximum output signal swing is constrained by the output voltage compliance of the DACs and the output dynamic range of the output amplifiers. The minimum voltage allowed at the outputs of the DACs is about 6 V. This constrains the minimum value of VMID to be 6 V. The output amplifiers will swing and settle cleanly, as described on the specification page, for output voltages within 1.5 V from each supply voltage rail.

For a given value of V_{MID}, the voltage required to saturate the video output voltages defines the maximum usable full-scale voltage. For example, if VMID is less than AVCC/2, the maximum value of VFS is (VMID – 1.5 V). If VMID is greater than AVCC/2, the maximum useful VFS is (AVCC – 1.5 – VMID). Figure 1 graphically describes these limiting factors.

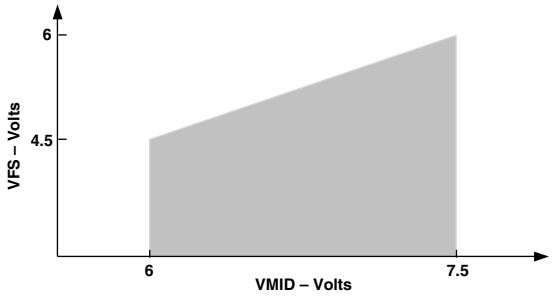


Figure 1. Valid Range for VMID with Respect to VFS (AVCC = 15 V)

ABSOLUTE MAXIMUM RATINGS[1]

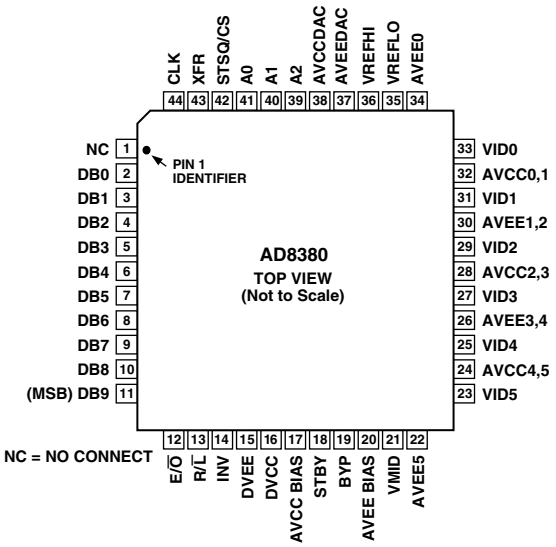
Supply Voltage AVCC–AVEE . . . . . 26 V
Internal Power Dissipation[2]
Quad Flat Package (S) . . . . . 1.7 W
Output Short Circuit Duration
. . . . . See Associated Text
Storage Temperature Range . . . . . –65°C to +125°C
Operating Temperature Range . . . . . 0°C to 85°C
Lead Temperature Range (Soldering 10 sec) . . . . . 300°C

NOTES

[1]Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

[2]Specification is for device in free air:
44-Lead MQFP Package: θ_{JA} = 73°C/W (Still Air), where $P_D = (T_J - T_A)/\theta_{JA}$. θ_{JC} = 22°C/W.

PIN CONFIGURATION



MAXIMUM POWER DISSIPATION

The maximum power that can be safely dissipated by the AD8380 is limited by the associated rise in junction temperature. The maximum safe junction temperature for plastic encapsulated devices is determined by the glass transition temperature of the plastic, approximately 150°C. Exceeding this limit temporarily may cause a shift in parametric performance due to a change in the stresses exerted on the die by the package. Exceeding a junction temperature of 175°C for an extended period can result in device failure.

Output Short Circuit Limit

The AD8380's internal short circuit limitation is not sufficient to protect the device in the event of a direct short circuit between a video output and a power supply voltage rail (V_{CC} or V_{EE}). Temporary short circuits can reduce an output's ability to source or sink current and, therefore, impact the device's ability to drive a load. Short circuits of extended duration can cause metal lines to fuse open, rendering the device nonfunctional.

To prevent these problems, it is recommended that a series resistor of 25 Ω or greater be placed as close as possible to the AD8380's video outputs. This will serve to substantially reduce the magnitude of the fault currents and protect the outputs from damage caused by intermittent short circuits. This may not be enough to guarantee that the maximum junction temperature (150°C) is not exceeded under all conditions. To ensure proper operation, it is necessary to observe the maximum power derating curve in Figure 2 below.

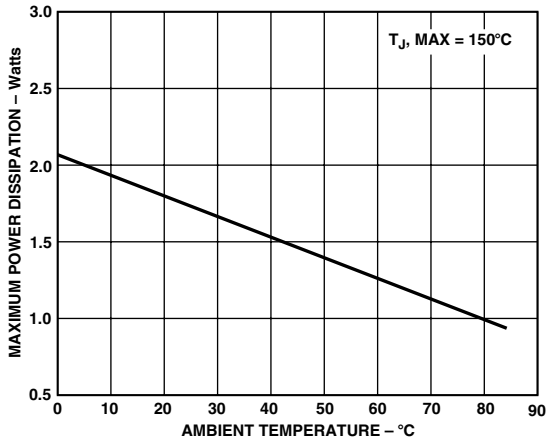


Figure 2. Maximum Power Dissipation vs. Temperature

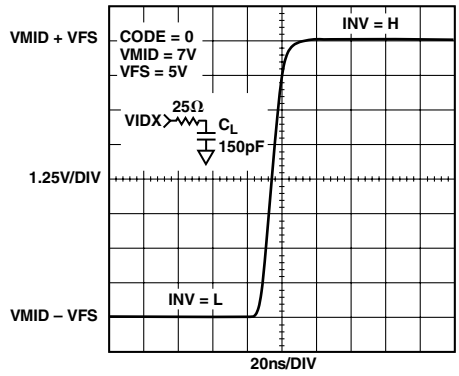
ORDERING GUIDE

Model	Temperature Range	Package Description	Package Option
AD8380JS	0°C to 85°C	44-Lead MQFP	S-44A

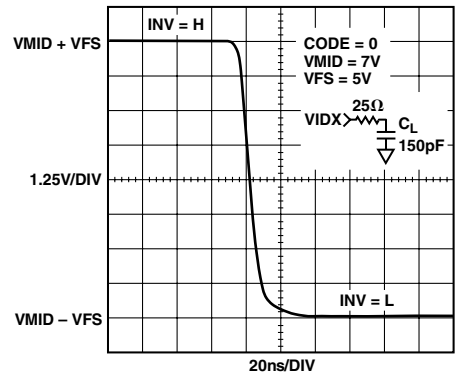
CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD8380 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high-energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.

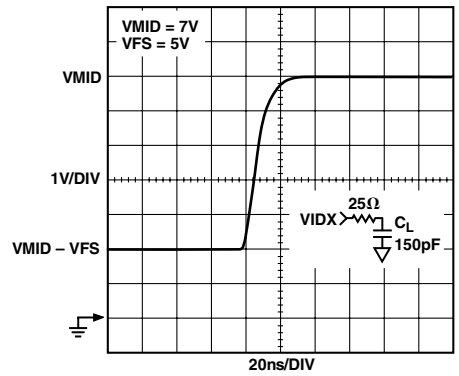




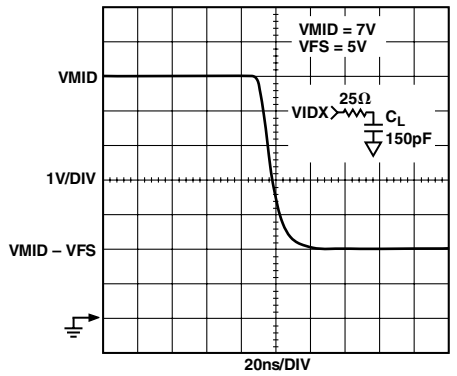
TPC 1. Invert Switching 10 V Step Response (Rise) at C_L



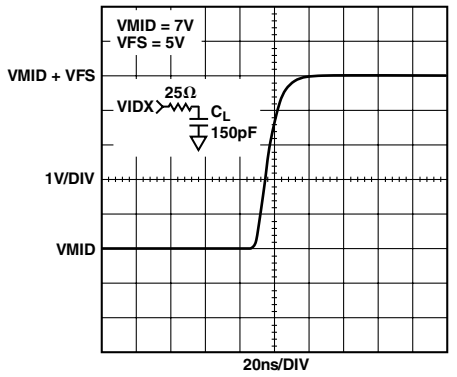
TPC 2. Invert Switching 10 V Step Response (Fall) at C_L



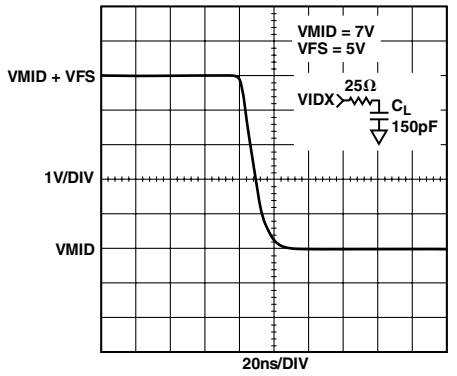
TPC 3. Data Switching Full-Scale Step Response (Rise) at C_L, INV = L



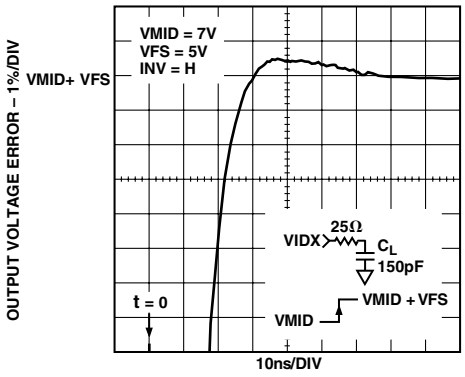
TPC 4. Data Switching Full-Scale Step Response (Fall) at C_L, INV = L



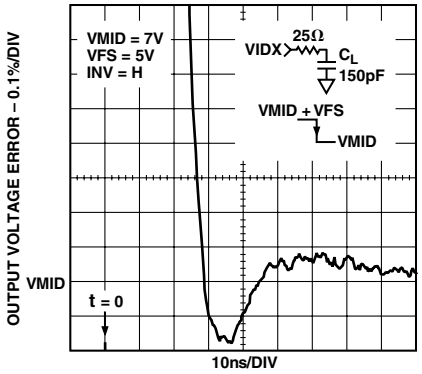
TPC 5. Data Switching Full-Scale Step Response (Rise) at C_L, INV = H



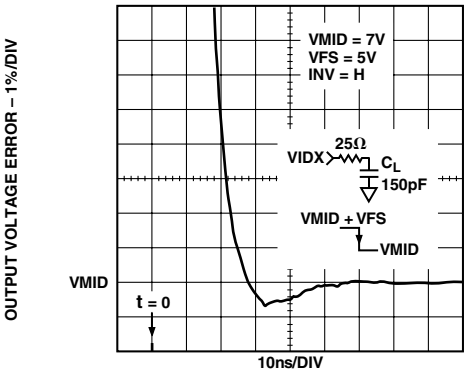
TPC 6. Data Switching Full-Scale Step Response (Fall) at C_L, INV = H



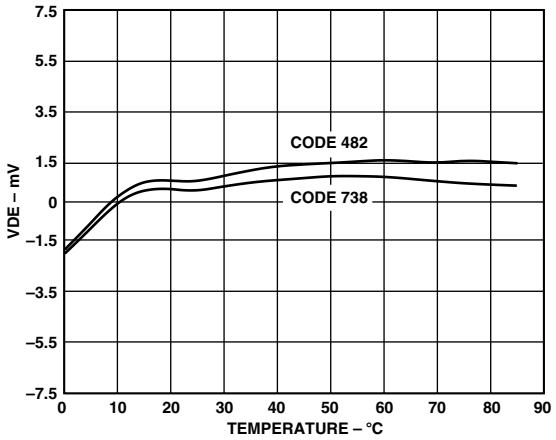
TPC 7. Output Settling Time Response to 1% of Full Scale (Rising Edge) at C_L



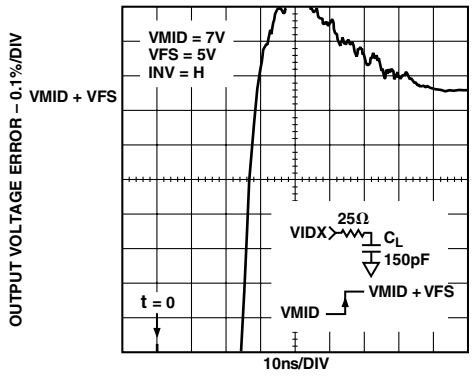
TPC 10. Output Settling Time Response to 0.25% of Full Scale (Falling Edge) at C_L



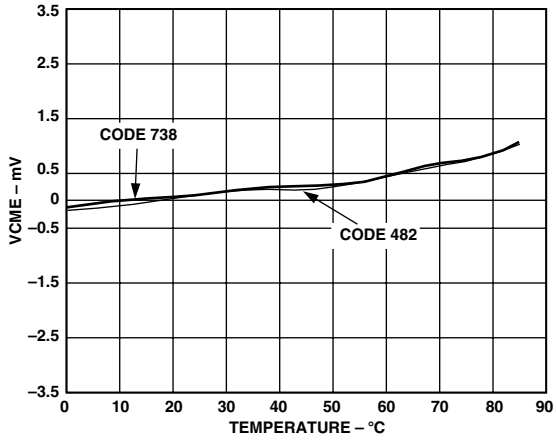
TPC 8. Output Settling Time Response to 1% of Full Scale (Falling Edge) at C_L



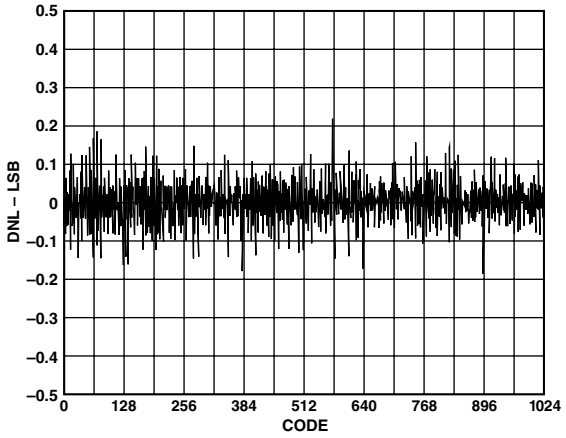
TPC 11. Differential Error Voltage (VDE) vs. Temperature



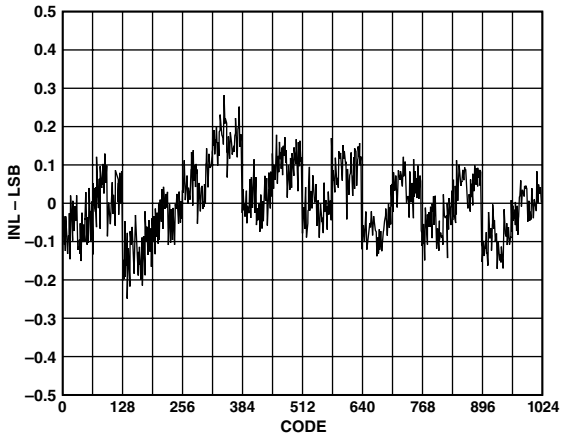
TPC 9. Output Settling Time Response to 0.25% of Full Scale (Rising Edge) at C_L



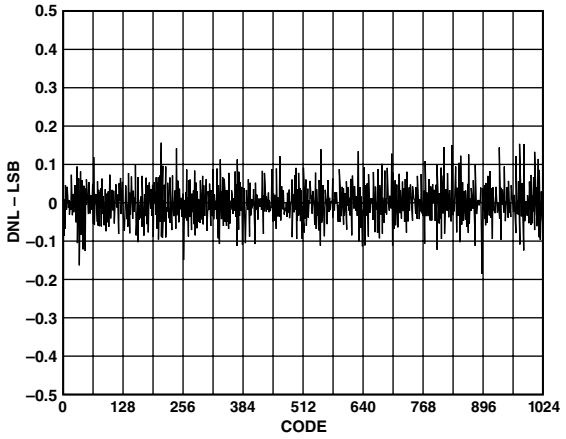
TPC 12. Common-Mode Error Voltage (VCME) vs. Temperature



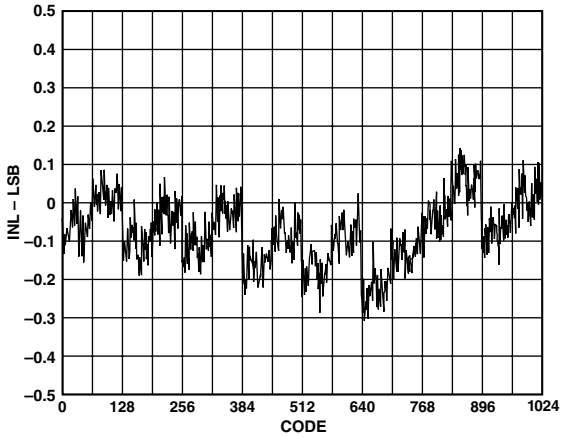
TPC 13. Differential Nonlinearity (DNL) vs. Code, INV = H



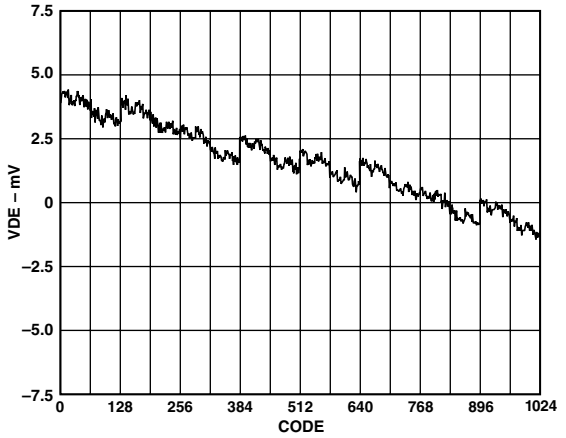
TPC 16. Integral Nonlinearity (INL) vs. Code, INV = H



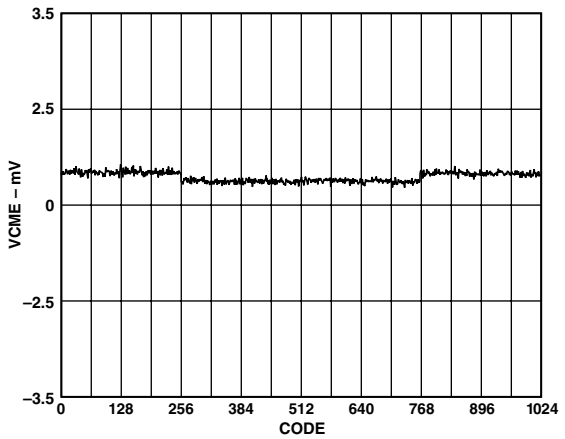
TPC 14. Differential Nonlinearity (DNL) vs. Code, INV = L



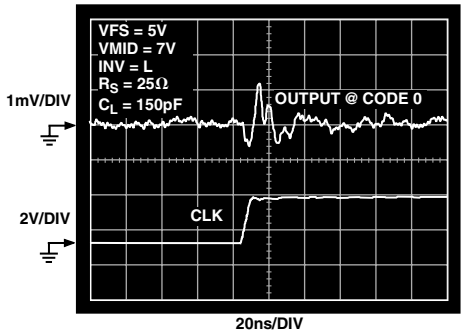
TPC 17. Integral Nonlinearity (INL) vs. Code, INV = L



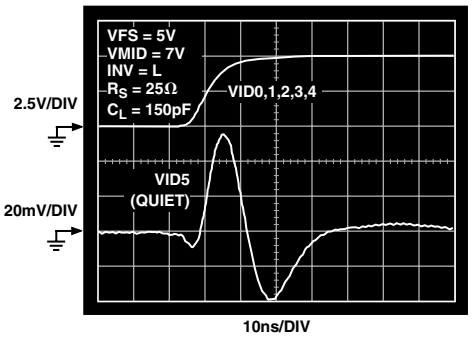
TPC 15. Differential Error Voltage (VDE) vs. Code



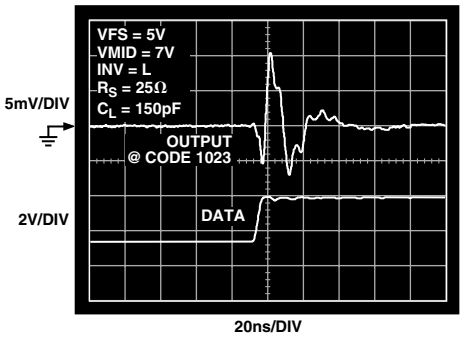
TPC 18. Common-Mode Error Voltage (VCME) vs. Code



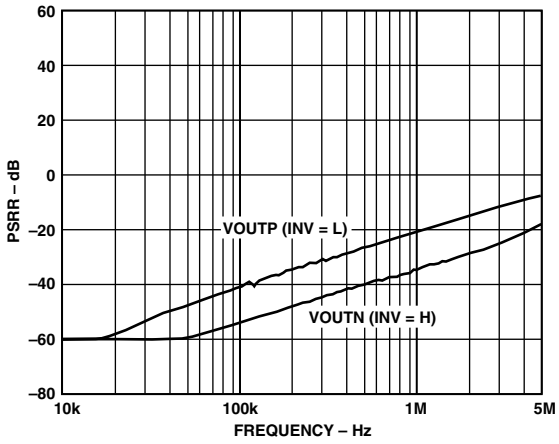
TPC 19. Clock Switching Transient (Feedthrough) at C_L



TPC 21. All-Hostile Crosstalk at C_L



TPC 20. Data Switching Transient (Feedthrough) at C_L



TPC 22. AVCC Power Supply Rejection vs. Frequency

THEORY OF OPERATION

The AD8380 is a system building block designed to directly drive the columns of poly-silicon LCD panels of the type popularized for use in data projectors. It comprises six channels of precision 10-bit digital-to-analog converters loaded from a single, high speed, 10-bit parallel input. Precision current feedback amplifiers providing well-damped pulse responses and rapid voltage settling into large capacitive loads buffer the six outputs. Excellent linearity performance and laser trimming of scale factors and output offsets at the wafer level ensure low absolute output errors over all input codes. Tight channel-to-channel matching in high channel count systems is guaranteed by reliance on an externally-applied voltage reference.

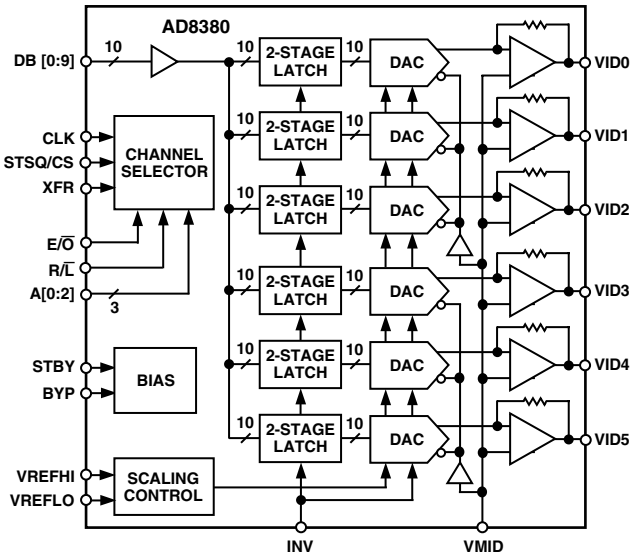


Figure 3. Top Level Block Diagram

Transfer Function

The transfer function of the AD8380 is made up of two regions of operation, in which the video output voltages are either above or below an output reference voltage externally applied at the VMID input.

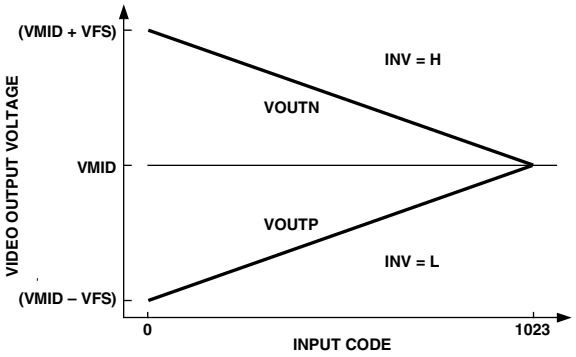


Figure 4. Definition of Output Transfer Function

The region over which the output voltage varies with input code is defined by the status of the INV input. When INV is low, the video output voltages rise from (VMID – VFS), (where VFS = the full-scale output voltage), to VMID as the input code increases from 0 to 1023. When INV is high, the output voltages drop from (VMID + VFS) to VMID with increasing code (see Figure 4).

For each value of input code there are then two possible values for the output voltage, depending on the status of INV. When INV is low the output is defined as VOUTP(N) where N refers to the input code, and the P refers to the positive slope of the voltage variation with code. When INV is high, the output is defined as VOUTN(N).

To best correlate transfer function errors to image artifacts, the overall accuracy of the AD8380 is defined by comparing the output voltages, VOUTP(N) and VOUTN(N), to each other and to their ideal values. Two parameters are defined, one dependent on the difference between the signal amplitudes at a particular code, and one dependent on their average value. These are VDE and VCME. Their defining expressions are:

$$VDE = [VOUTN(N) - VOUTP(N)]/2 - [(1 - N/1023) \times VFS]$$

where

N = input code, and $VFS = 2 \times (VREFHI - VREFLO)$

$$VCME = [[VOUTN(N) + VOUTP(N)]/2 - VMID] \times (1/2)$$

where

$VMID$ = midpoint reference voltage for the video outputs.

Setting the Full-Scale Output

The full-scale output voltage (VFS), which defines the maximum output voltage excursion for a full code input transition, is defined as twice the voltage difference between the VREFHI and VREFLO inputs.

Operating Modes, Control Logic and DAC Latches

Control logic included on the AD8380 chip facilitates channel loading in ascending or descending order (for image mirroring), data loading on rising or falling clock edges (for even/odd word loading), and addressing and loading individual channels (for system testing or debugging). The on-chip logic makes it easy to build systems requiring more than six drive channels per color.

DAC latches are of a two-stage master-slave design that guarantees all channel outputs are updated simultaneously.

SVGA System Operation

An SVGA system is characterized by the requirement of six channels of panel drive for each displayed color. Such a system would use a single AD8380 per color.

With E/$\overline{O}$ and all address bits A[0:2] set high, channel loading commences on the first rising edge of CLK following a valid assertion of the Start Sequence (STSQ) input. The second stage latches, and therefore the video outputs, are updated on the first falling edge of the clock following a valid Transfer (XFR) signal. (See Figure 5 for signal timing details.)

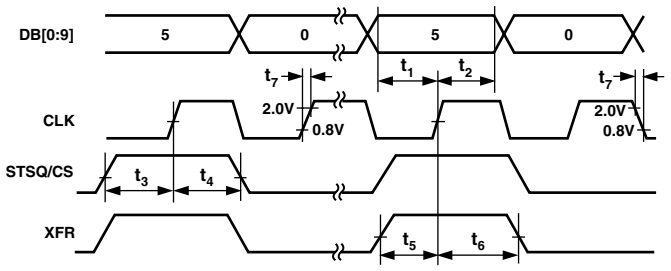


Figure 5. Sequenced SVGA Timing (A[0:2] = HIGH, E/$\overline{O}$ = HIGH, See Table I)

Table I. Sequenced SVGA Data Byte to Channel Assignment

Channel Number		Data Byte Number
E/$\overline{O}$ = HIGH	VID0	0
R/$\overline{L}$ = LOW	VID1	1
	VID2	2
	VID3	3
	VID4	4
	VID5	5

Load Sequence Switching (Right/Left Control)

To facilitate image mirroring, the order in which channels are loaded can be easily switched. When the voltage on the right/left control input (R/$\overline{L}$) is low, the internal sequencer will load data starting with Channel 0 and counting up to Channel 5. When this voltage is high, channel loading will be in reverse order, from Channel 5 down to Channel 0.

XGA System Operation

In an XGA system, twelve column drivers (two AD8380s) are required for each color (refer to Figure 6). An "even/odd" system, in which one AD8380 drives even numbered columns and another drives odd numbered columns, can be easily implemented as detailed in Figures 7 and 8. A clock at one-half the pixel rate is applied to the CLK input. Even bytes are loaded on the rising edge of the clock, while odd bytes are loaded on the falling edge. Identifying whether a chip is to load on rising or falling edges is done by setting the proper level on the E/$\overline{O}$ input.

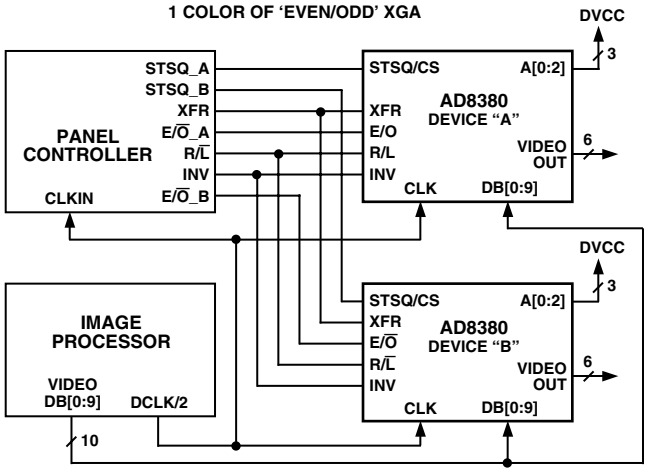


Figure 6. Even/Odd: Outputs of Devices A and B are Configured as Even and Odd Data Channels and Loading Sequence Is Defined by Status of E/$\overline{O}$ and R/$\overline{L}$ Inputs

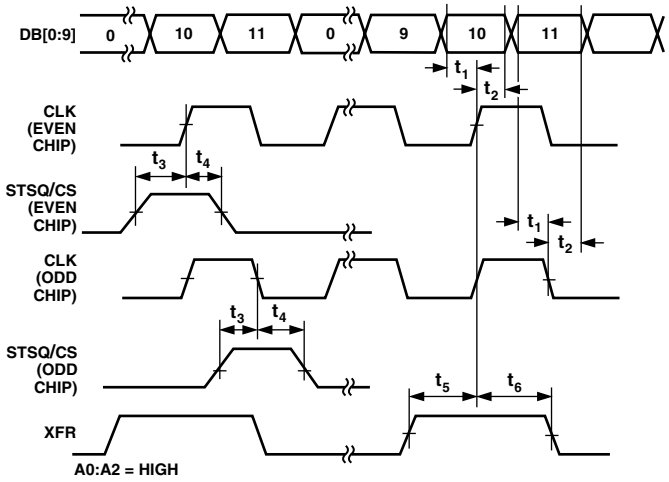


Figure 7. Sequenced Even/Odd XGA Timing, A[0:2] = HIGH (See Table II)

Table II. Sequenced Even/Odd XGA Data Byte to Channel Assignment

Channel Number		Data Byte Number R/$\overline{L}$ = LOW	Data Byte Number R/$\overline{L}$ = HIGH
E/$\overline{O}$ = HIGH	VID0	0	10
	VID1	2	8
	VID2	4	6
	VID3	6	4
	VID4	8	2
	VID5	10	0
E/$\overline{O}$ = LOW	VID0	1	11
	VID1	3	9
	VID2	5	7
	VID3	7	5
	VID4	9	3
	VID5	11	1

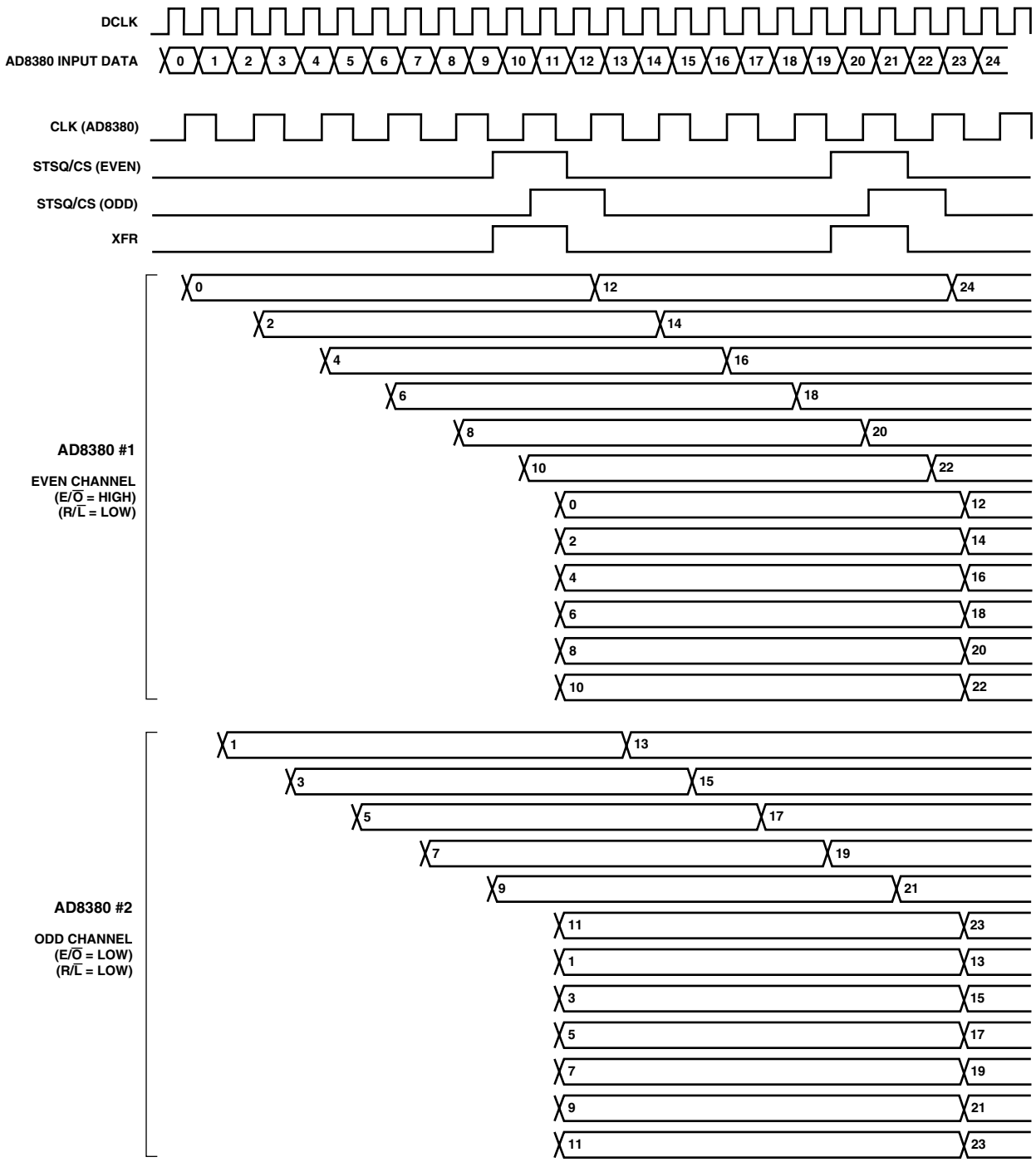


Figure 8. Operation of Even/Odd XGA System

SXGA and Beyond

Very high resolution display systems can be built using the E/$\overline{O}$ XGA system as a model. By using four AD8380s, twenty-four columns can be driven together for an SXGA display. Two would be designated for even columns and two for odd. Four separate STSQ signals would be used to coordinate data loading with a single XFR to synchronize updating of output voltages.

Using a single external voltage source to drive the VREF inputs on all drivers for a particular color and a single voltage source for all their VMID inputs, will guarantee matching for all channels. The exceptional accuracy of the AD8380's transfer function will ensure that high channel count systems can be built without fear of image artifacts resulting from channel-to-channel matching errors.

Direct Channel Loading

For debug or characterization purposes, it may be desirable to load data directly into a single channel without requiring exercise of the STSQ and XFR inputs. This can be done by applying dc logic high levels to the STSQ and XFR inputs, and addressing the desired channel through the A[0:2] inputs. Data will then be loaded into the selected channel on each falling edge of the CLK signal.

The maximum rate at which a channel can be updated will be limited by the settling time of the output amplifiers.

Addressed Channel Loading

The direct channel loading method can be extended. Channels may be loaded in an arbitrary sequence through the use of an active XFR signal with STSQ set to a high level. Use the A[0:2] inputs to define the desired channel sequence. Data will be loaded on the falling edge of CLK into the channel whose address was valid on the preceding rising edge of CLK. All channel outputs are then updated together by qualification of a valid XFR signal. See Figure 9 for timing details.

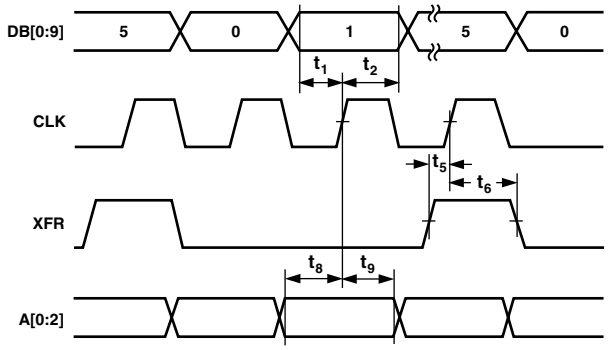


Figure 9. Addressed Channel Timing (E/$\overline{O}$ = HIGH, STSQ/CS = HIGH)

Standby Mode

A high level applied to the standby (STBY) input will turn off most of the internal circuitry, dropping the quiescent power dissipation to a few milliwatts. Since both digital and analog circuits are debiased, all stored data will be lost. Upon returning STBY to a low level, normal operation is restored.

APPLICATION

The AD8380 is a mixed-signal, high speed, very accurate device with multiple channels. In order to realize its specifications, it is essential to use a properly designed circuit board.

Layout and Grounding

The analog and digital sections of the AD8380 are pinned out on approximately opposite sides of the package. When laying out a circuit board, please keep these sections separate from each other to minimize crosstalk and noise coupling of the digital input signals into the analog outputs.

All signal trace lengths should be made as short and direct as possible to prevent signal degradation due to parasitic effects. Please note that digital signals should not cross or be routed near analog signals.

It is imperative to provide a solid ground plane under and around the part. All of the ground pins of the part should be directly connected to the ground plane with no extra signal path length. For conventional operation, this includes the pins DVEE, AVEEDAC, AVEEBIAS, AVEE0, AVEE1,2; AVEE3,4; and AVEE5. The return currents for any of the signals for the part should be routed close to the ground pin for that section to prevent stray signals from appearing on other ground pins.

Power Supply Bypassing

The AD8380 has several power supply and reference voltages that must be properly bypassed to the ground plane for optimum performance. The bypass capacitor for each supply pin, as well as VREFHI, VREFLO, and VMID, should be connected as close as possible to the IC pins and directly to the ground plane. A 0.1 µF capacitor, preferably a ceramic chip, should be used to minimize lead length.

To provide low frequency, high current bypassing, larger value tantalum capacitors should also be used. These should be connected from the supply to ground, but it is not necessary to place these close to the IC pins. Stray inductance will not greatly affect their performance. The high current outputs should be bypassed with these capacitors. It is recommended that two 22 µF tantalum capacitors be placed from the AVCC supply to ground at either end of the output side of the IC. AVCCBIAS and AVCCDAC should each have a 10 µF tantalum bypass capacitor to ground. See Figure 10.

VREFHI Reference Distribution

In a system that uses more than one AD8380 per color, it is important that all of the AD8380 devices operate from equal reference voltages to ensure that the video outputs are well matched. VREFLO is not a concern due to its high input resistance and very low bias current. Therefore, it is not likely that there will be significant dc voltage drops in the circuit traces to that supply. It is recommended to have good local supply bypassing at each AD8380 from their respective VREFLOs to ground.

The higher input current that flows in the VREFHI circuit requires that this be laid out more carefully. VREFHI connects internally to a 20 kΩ resistor for each of the six channels to provide an input resistance of about 3.3 kΩ. Thus with a (VREFHI – VREFLO) voltage of 2.5 V (to yield a VFS of 5.0 V), about 750 µA will flow into each VREFHI circuit.

In order to obtain the best matching, the traces to each of the VREFHI pins of the AD8380s should be connected by an approximately same length and same width circuit trace in a "star" configuration. The source of the VREFHI voltage should be at the center of the "star." Therefore, the VREFHI currents for two devices will not share a significant length of circuit trace, and each trace will provide an approximately equal voltage drop.

In addition, if the VREFHI traces must be long, then the traces should be widened to minimize differences in the voltage drops due to differences in the VREFHI input currents of different AD8380s. The dc resistance of these traces should be less than 100 mΩ. If the VREFHI input current is about 1 mA, then the voltage drop will be about 100 μV.

For example, if a trace length is 5 in. long (13 cm.), then the trace width for a 1 oz. copper foil should be wider than 0.025 in. (0.7 mm) in order to keep the trace impedance below 100 mΩ.

Driving a Capacitive Load

A purely capacitive load can react with output impedance of the AD8380 resulting in overshoot and ringing in its step response. To minimize this effect, and optimize settling time, it is recommended that a 25 Ω resistor be placed in series with each of the driver's outputs as shown in Figure 10.

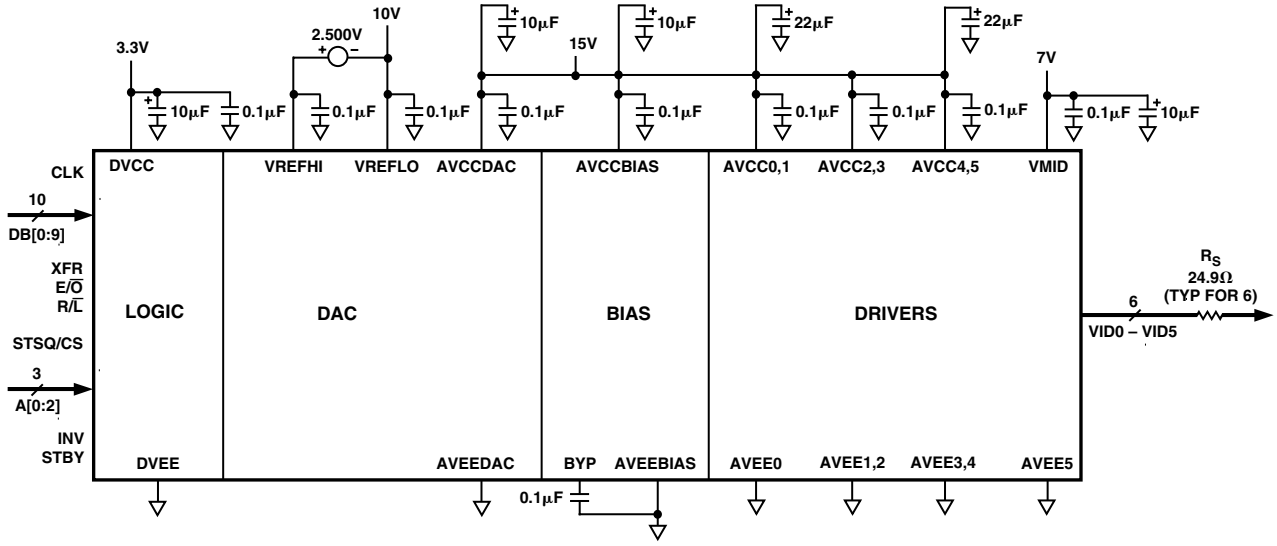
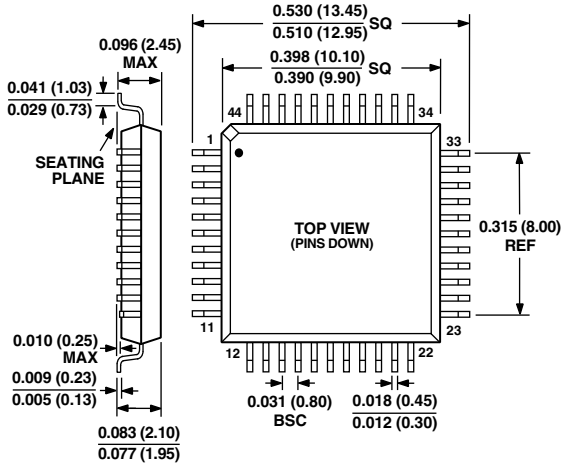


Figure 10. Interface Drawing

OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).

44-Lead MQFP
(S-44A)



AD8380–Revision History

Location	Page
Data sheet changed from REV. A to REV B.	
Single-Channel Block Diagram section and graphic removed	9

C01091–0–4/01(B)

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